

MINUTES
 S-1 General Session Committee
 Holiday Inn Riverwalk
 San Antonio, TX 78205
 Tuesday Sept 25, 2007

1.0 Call to Order - Circulate Membership Roster

Meeting called to order at 8:10 am by Chairman Mike Lauri

2.0 Committee Organization and Procedures

2.1 Membership Intros were conducted and Roster circulated.

The attendance was as follows:

NAME	COMPANY
Michael Lauri	IBM
Paul Krystek	IBM via Phone
Dave Richardson	Vishay
Bill Gisseler	TDK
Mike Cannon	TDK
Chris Reynolds	AVX
Carl Lindquist	SOC America Inc.
Jayson Young	Kemet Electronics
Joe Biernacki	Stackpole Electronics
Ralph Justus	ECA
Mary Carter Berrios	Kemet Electronics
Ed Mikoski	ECA
Ted Coler	Vishay
Kurt Zipp	MGA
Steven Kummerl	TI

A quorum was present.

<u>Member Organizations Present</u>	<u>Present at this Meeting (Fall 2007)</u>	<u>Present at this Meeting (Spring 2007)</u>	<u>Present at this meeting (Fall 2006)</u>
ATC	N	Y	Y
AVX	Y	Y	Y
Cornell Dubilier	N	Y	Y
IBM	Y	Y	Y
Intel	N	Y	Y
Kemet	Y	Y	Y
KOA Speer Electronics	N	Y	Y
SOC America Inc.	Y	Y	Y
SEI Electronics	Y	Y	Y
TDK	Y	Y	Y
TI	Y	N	N

Vishay	Y	Y	Y
Yageo	N	Y	Y

<u>Member Organizations Absent</u>	<u>Present at this meeting?(Fall 2007)</u>	<u>Present at this meeting?(Spring 2007)</u>	<u>Present at this meeting? (Fall 2006)</u>
Cooper Bussmann	N	N	N
Murata Electronics	N	N	Y
Panasonic	N	N	Y
Rohm Electronics	N	N	N
Epcos	N	N	Y
Mini-Systems Inc	N	N	Y

<u>Other Organizations Present</u>
ECA
MGA

2.2 Approval of Agenda and Previous Minutes – Approved.

2.3 Correspondence – Mark Crawford Dept. of Commerce asked ECA to survey our members on counterfeit parts in military high reliability applications. ECA will be in touch with this person to follow up on the survey and questions they would like to see answered by our committee members.

Action Item: ECA to follow up with Mark Crawford on counterfeit parts survey.

2.4 Review of Committees Scope- To provide leadership and direction for passive component standards engineering working groups. The Committee will offer an opportunity for creating a unifying environment for interaction between all passive component users and producers. No changes required at this time.

3.0 ECA Update/Presentations - Ralph Justus of ECA gave an update on the EIA/ECA environmental issues. TIA made a presentation to absorb the EIA/ECA environmental activities (track database). The JIG101 hazardous materials and substances document will not go to TIA and will be kept at ECA. This JIG101 document is currently in revision now. Also TC111 deals with environmental issues in the electronics area.

4.0 Presentations

4.1 Mary Carter-Berrios of Kemet presented on China Rohs and Reach. This presentation focused on chemical suppliers must register their materials. This chemical registration will affect component suppliers and their declarations. A substance of very high concern (SVHC) list will be generated within the next year (Jun to Dec 2008 timeframe). The summary is that full material disclosure declarations are wanted in the industry. To do so, component manufactures have to fully disclose all chemicals, materials, processes etc. (ie....their primary IP knowledge) which is in many cases proprietary.

Dave Richardson will send out an email to attempt to locate the correct persons at each supplier who are going to have to deal with this China Rohs/Reach issue in the very near future. The goal here would be to attempt to have a standard position for the industry on this issue.

4.2 Mary Carter-Berrios of Kemet and Dave Richardson of Vishay presented a Summary of DOE for AEC on Moisture Preconditioning prior to Reliability Testing for Tantalum Capacitors. This presentation showed the data taken on several industry suppliers parts (AVX, Kemet, Vishay) which showed that moisture preconditioning is not applicable to non-hermetic tantalum SMT parts since all suppliers had failures. So if the AEC Q200 spec required this as the preconditioning requirements, they would have no qualified tantalum suppliers to use on their products.

5.0 Old Business

5.1 PN5149 – J-STD-075 new joint standard on Assembly Processing, Evaluation and Classification of Non-IC Electronic Components Update – Paul Krystek via phone gave an update on the status of this new document. It is currently in the ECA 30 day voting process. To date we have 4 approvals (SOC, SEI, Vishay, IBM) , 2 approvals with editorial comments (Kemet, EPOS) There are no technical comments to date. We are missing votes from CDE, AVX, TDK, EPCOS, Yageo, ATC, KOA and Intel. IBM spoke with the members present (CDE, TDK, AVX) to get their vote in by the 10/4 deadline. All editorial comments were taken and approved and incorporated into this document.

5.2 Status of AEC Change Notification Process (PCN) – Kemet – Mary Carter-Berrios gave an update on the automotive qualification and change notification process (PCN). Automotive customers surveyed state that 80% of their problems are due to supplier process changes. They say there are 1500-2000 open a month, with 200-500 more submitted monthly. Automotive companies cannot keep up with these changes. This is impacting many of the suppliers in implementing changes. There is a change of PPAP manual changes to include even more divulging of more information about changes. Kemet went to the AEC Technical Symposium in May to push for changes to the Q200 document. Kemet showed that their PCN process is broken and dysfunctional. They only process 10% of the PCNs within 6 months with 90% of the PCNs are taking greater than 6 months to signoff. These delays in processing PCNs prohibit their implementation of continuous improvement, Zero defect programs and any associated cost reduction activities. It is also costing the suppliers more money to track down all these PCNs at AEC member companies. The bottom line is that the AEC Q200 needs to change and faster approvals are needed. AEC did not disagree with these findings.

5.3 Status of PN5165 China RoHS Environmental Friendly Use Period (EFUP) Marking Requirements component bulletin CB24. This document was written by Mike Griffith of KOA and was suppose to be posted on the ECA bulletin board for commenting. Well, a long train of a note was posted, but the document never got posted to the bulletin board. Therefore the members never reviewed this document. Therefore we will postpone our vote on the release to the Spring 2008 meeting.

Chairmen M. Lauri will send the preliminary document as written to ECA for member distribution and commenting and reposting to ECA message bulletin board.

6.0 New Business

6.1 Carl Lindquist Chairmen of P14 brought up that the P14 committee has a new scope. The new scope for P14 is now as follows: This committee covers the setting of standards and specifications for supplementary Over-Current type devices to be used in low voltage applications in electric and electronic equipment. The committee shall not develop standards and specifications for branch circuit protection or panel mounted devices that are covered under the National Electric code NFPA 70.

The committee voted to approve this new scope as written unanimously.

7.0 Future Meetings – The next meeting Spring 2008 will be at the Brown Hotel, 335 West Broadway, Louisville, Ky 40202 on March 31 through April 3, 2008. The committee voted on Holding the Fall 2008 meeting in Park City, UT as the primary site, with the alternate site being Saratoga, NY.

8.0 Action Items –

1. ECA to follow up with Mark Crawford on counterfeit parts survey.
2. Dave Richardson will send out an email to attempt to locate the correct persons at each supplier who are going to have to deal with this China Rohs/Reach issue
3. Chairmen M. Lauri will send the preliminary document as written to ECA for member distribution and commenting and reposting to ECA message bulletin board.

9.0 Adjournment – Meeting was adjourned at 11:05 AM.